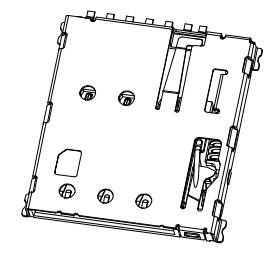
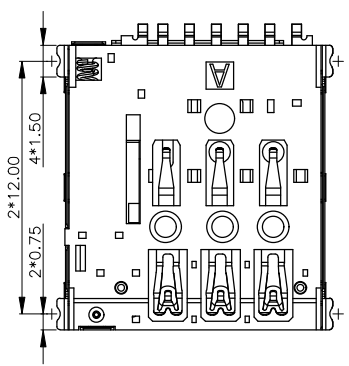
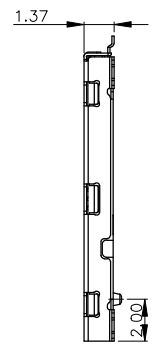
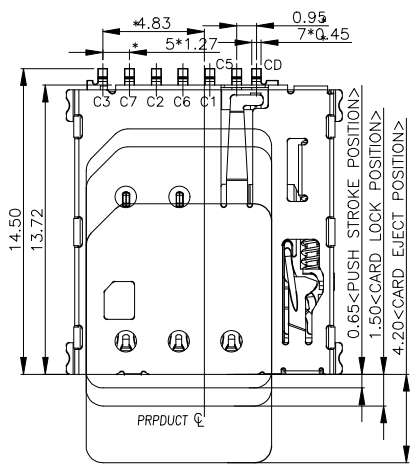




REV.	ECN NO OR DESCRIPTION	REVISED	DATE

A

A



3D VIEW

NOTES:

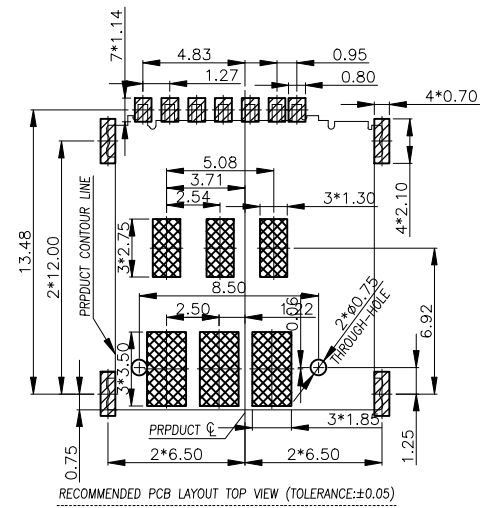
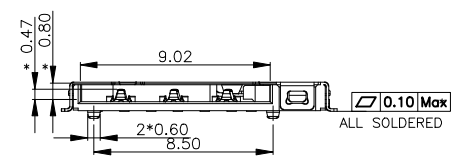
- MATERIAL:
HOUSING: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel
- PLATING:
Terminal: 50u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
Shell: 30u" Ni UNDERPLATED OVERALL
G/F PLATED ON CONTACT AREA AND SOLDER AREA
- TECHNICAL SPECIALITY:
RATED VOLTAGE: 30V AC MAX.
CURRENT RATING: 0.5A MAX.
INSULATION RESISTANCE: 1000MΩ MIN
CONTACT RESISTANCE: 50mΩ MAX
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
OPERATING TEMPERATURE:
-25°C~+85°C Humidity 80% R.H MAX
- DIMENSIONS WITH MARK * "MUST BE MEASURE BY QC AND IPQC"

B

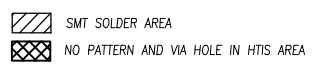
B

C

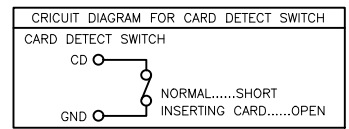
C



RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)
RECOMMENDED METAL MASK T=0.12mm

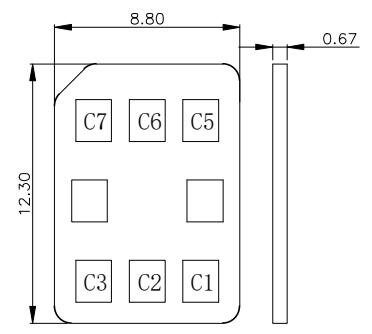


PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O



D

D



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.35	X :±2°
X.X :±0.25	X.X :±1°
X.XX :±0.15	

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE: 137 NANO SIM CARD CONNECTOR

DWN	xiong	PART NO. SNO-1351
CHKD	lee	SCALE:1:1 UNIT: mm
APVD	wang	SIZE: A4 SHEET:10F 1

CUSTOMER COPY